

09-03-1999

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To the Honorable 101134919

Please record the attached original document

marks:  
thereof.10510 U.S. PTO  
09/30/3232  
08/26/99

1. Name of conveying party(ies):

OH, Ki-Young

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other:

Execution Date: August 19, 1999

2. Name and address of receiving party(ies)

Name: HYUNDAI MicroElectronics, Co., Ltd

Internal Address:

Street Address: 1 Hyangjeong-dong, Hungduk-gu,  
Cheongju-shi

City: Chungcheongbuk-do

State:

ZIP:

Country: Korea

Postal Code:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: August 19, 1999

A. Patent Application No(s).

B. Patent No(s).

09/383232

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: BIRCH, STEWART, KOLASCH &amp; BIRCH, LLP

Street Address: P.O. BOX 747

City: FALLS CHURCH State: VA ZIP: 22040-0747

Country: USA

6. Total No. of applications/patents involved: One (1)

7. Total fee (37 C.F.R. § 3.41): \$40.00

☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number: 02-2448

(Attach triplicate copy of this page  
if paying by deposit account)

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Terry L. Clark, #32,644

Name of Person Signing/Reg. No.

Signature

August 26, 1999

Date

Total number of pages including cover sheet, attachments, and document: Three (3)

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments  
Washington, DC 20231

09/02/1999 DBUTLER 00000009 09383232

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TLC/tnp

## ASSIGNMENT

Application No. NewFiled 8/26/99Insert Name(s)  
of Inventor(s)WHEREAS, Ki-Young OHInsert Title  
of Invention

hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in \_\_\_\_\_

CAPACITOR OF SEMICONDUCTOR DEVICE AND METHOD OFFABRICATING THE SAME

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

Insert Date  
of Signing of  
Applicationon August 19, 1999; andInsert Name  
of AssigneeWHEREAS, HUNDAI MicroElectronics Co., Ltd.Insert Address  
of Assigneeof 1 Hyangjeong-dong, Hungduk-gu, Cheongju-shi,  
Chungcheongbuk-do, Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

CHECK BOX  
IF APPROPRIATE☒ in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date <u>8/19/99</u>	Name of Inventor <u>Ki-Young OH</u> <u><i>Ki-Young OH</i></u> (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)
Date _____	Name of Inventor _____ (signature)